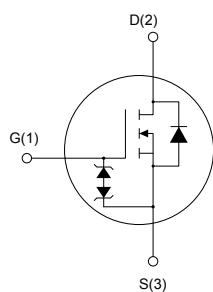
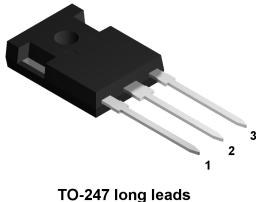


Automotive-grade N-channel 600 V, 37 mΩ typ., 66 A, MDmesh™ DM2 Power MOSFET in a TO-247 long leads package

Features



AM01476v1_No_tab

Order code	V _{DS}	R _{DS(on)} max.	I _D	P _{TOT}
STWA72N60DM2AG	600 V	42 mΩ	66 A	446 W

- AEC-Q101 qualified
- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

Applications

- Switching applications

Description

This high-voltage N-channel Power MOSFET is part of the MDmesh™ DM2 fast-recovery diode series. It offers very low recovery charge (Q_{rr}) and time (t_{rr}) combined with low $R_{DS(on)}$, rendering it suitable for the most demanding high-efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

Product status link	
STWA72N60DM2AG	
Product summary	
Order code STWA72N60DM2AG	
Marking	72N60DM2
Package	TO-247 long leads
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at $T_{case} = 25^\circ\text{C}$	66	A
	Drain current (continuous) at $T_{case} = 100^\circ\text{C}$	42	
$I_{DM}^{(1)}$	Drain current (pulsed)	220	A
P_{TOT}	Total dissipation at $T_{case} = 25^\circ\text{C}$	446	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	50	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	
T_{stg}	Storage temperature range	-55 to 150	$^\circ\text{C}$
T_j	Operating junction temperature range		

1. Pulse width is limited by safe operating area.
2. $I_{SD} \leq 66 \text{ A}$, $di/dt = 800 \text{ A}/\mu\text{s}$, V_{DS} peak < $V_{(BR)DSS}$, $V_{DD} = 80\% V_{(BR)DSS}$.
3. $V_{DS} \leq 480 \text{ V}$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.28	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	50	

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	8	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50 \text{ V}$)	1500	mJ

2

Electrical characteristics

(T_{case} = 25 °C unless otherwise specified)**Table 4. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	V _{GS} = 0 V, I _D = 1 mA	600			V
I _{DSS}	Zero gate voltage drain current	V _{GS} = 0 V, V _{DS} = 600 V			10	μA
		V _{GS} = 0 V, V _{DS} = 600 V, T _C = 125 °C ⁽¹⁾			100	
I _{GSS}	Gate-body leakage current	V _{DS} = 0 V, V _{GS} = ±25 V			±5	μA
V _{G(th)}	Gate threshold voltage	V _{DS} = V _{GS} , I _D = 250 μA	3	4	5	V
R _{D(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 33 A		37	42	mΩ

1. Defined by design, not subject to production test.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C _{iss}	Input capacitance	V _{DS} = 100 V, f = 1 MHz, V _{GS} = 0 V	-	5508	-	pF
C _{oss}	Output capacitance		-	241	-	
C _{rss}	Reverse transfer capacitance		-	2.8	-	
C _{oss eq.} ⁽¹⁾	Equivalent output capacitance	V _{DS} = 0 to 480 V, V _{GS} = 0 V	-	470	-	pF
R _G	Intrinsic gate resistance	f = 1 MHz open drain	-	2	-	Ω
Q _g	Total gate charge	V _{DD} = 480 V, I _D = 66 A, V _{GS} = 0 to 10 V (see Figure 14. Test circuit for gate charge behavior)	-	121	-	nC
Q _{gs}	Gate-source charge		-	26	-	
Q _{gd}	Gate-drain charge		-	61	-	

1. C_{oss eq.} is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t _{d(on)}	Turn-on delay time	V _{DD} = 300 V, I _D = 33 A, R _G = 4.7 Ω, V _{GS} = 10 V (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	32	-	ns
t _r	Rise time		-	67	-	
t _{d(off)}	Turn-off delay time		-	112	-	
t _f	Fall time		-	10.4	-	

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		66	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		220	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0 \text{ V}$, $I_{SD} = 66 \text{ A}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 66 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$,	-	150		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 480 \text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	0.75		μC
I_{RRM}	Reverse recovery current	$I_{SD} = 66 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$, $V_{DD} = 480 \text{ V}$, $T_j = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	10.5		A
t_{rr}	Reverse recovery time	$I_{SD} = 66 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$,	-	250		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 480 \text{ V}$, $T_j = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	2.5		μC
I_{RRM}	Reverse recovery current	$I_{SD} = 66 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$, $V_{DD} = 480 \text{ V}$, $T_j = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	20.7		A

1. Pulse width is limited by safe operating area.

2. Pulse test: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

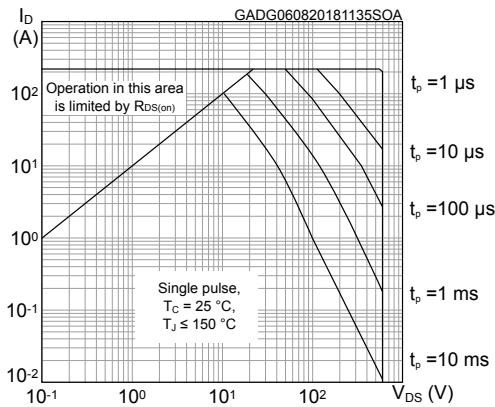


Figure 2. Thermal impedance

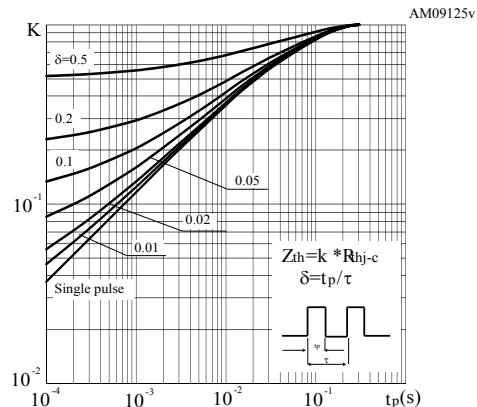


Figure 3. Output characteristics

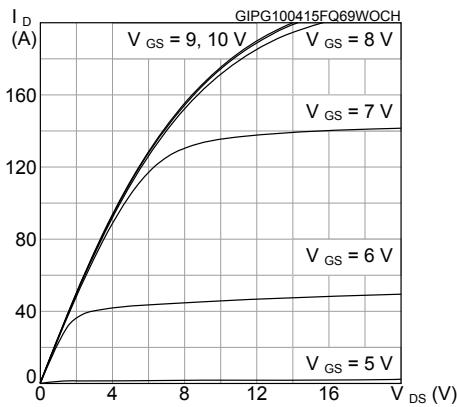


Figure 4. Transfer characteristics

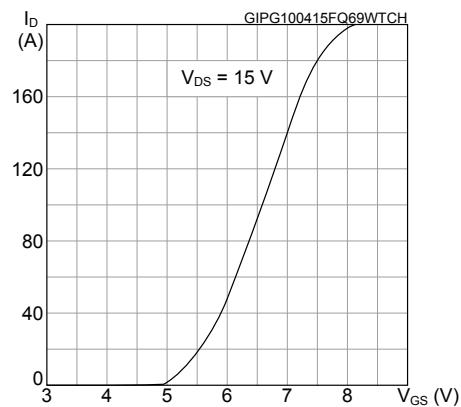


Figure 5. Gate charge vs gate-source voltage

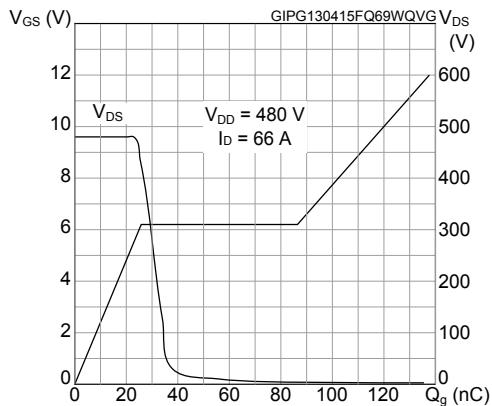


Figure 6. Static drain-source on-resistance

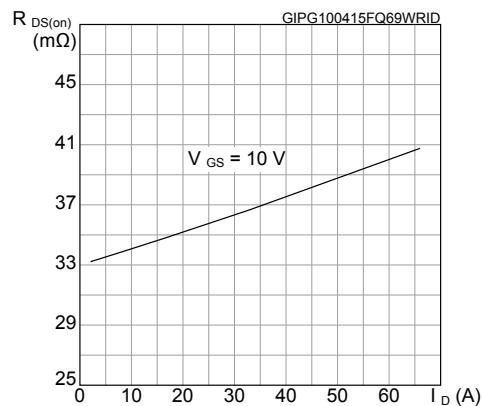
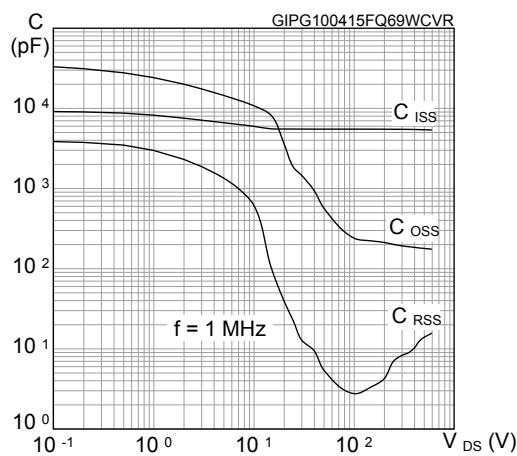
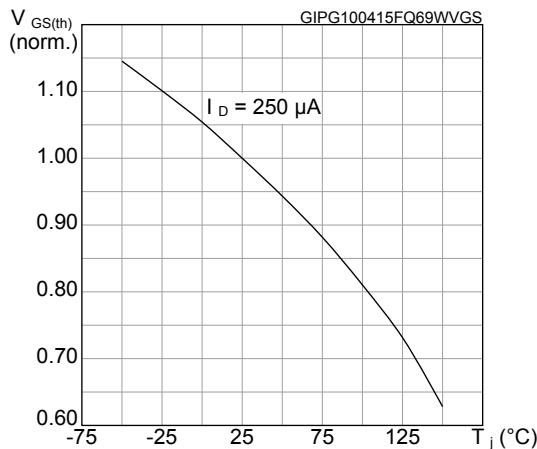
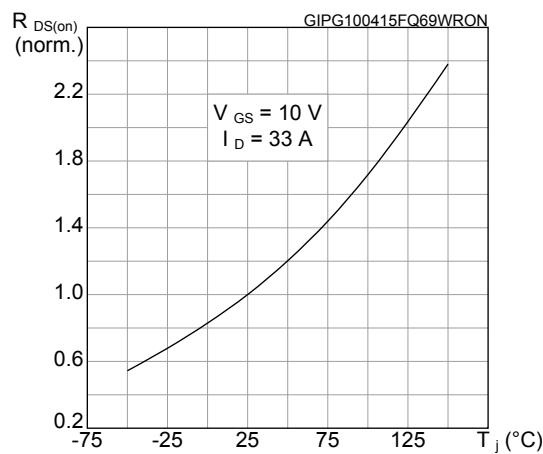
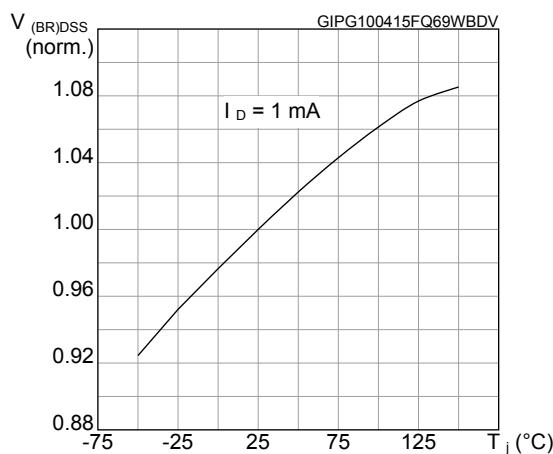
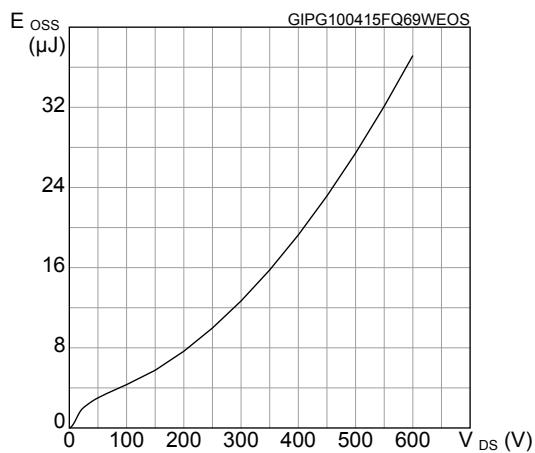
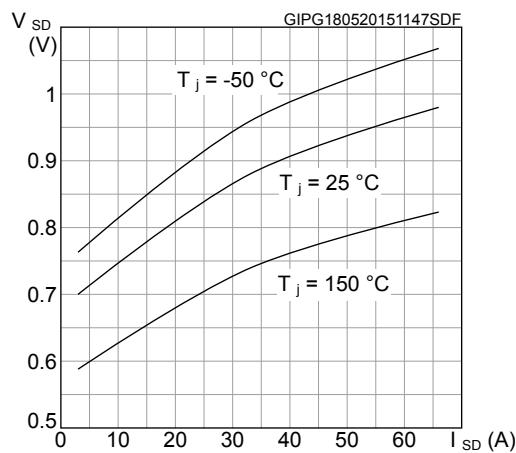
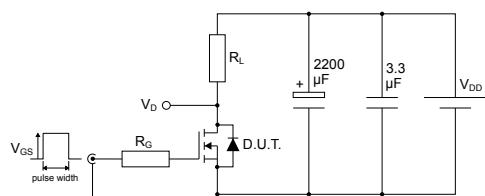


Figure 7. Capacitance variations

Figure 8. Normalized gate threshold voltage vs temperature

Figure 9. Normalized on-resistance vs temperature

Figure 10. Normalized V_(BR)DSS vs temperature

Figure 11. Output capacitance stored energy

Figure 12. Source- drain diode forward characteristics


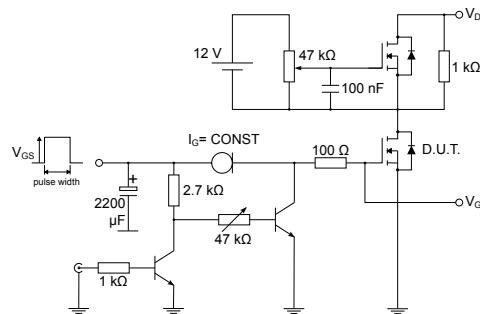
3 Test circuits

Figure 13. Test circuit for resistive load switching times



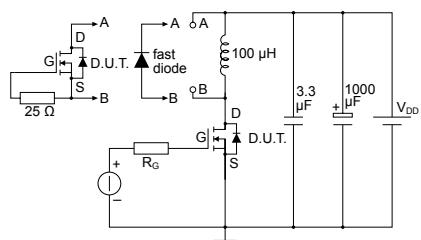
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Figure 14. Test circuit for gate charge behavior



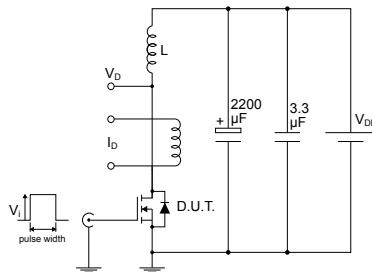
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Figure 15. Test circuit for inductive load switching and diode recovery times



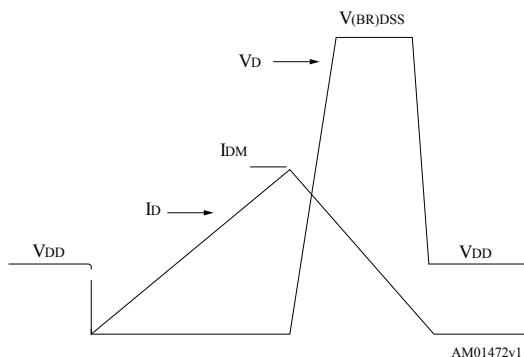
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Figure 16. Unclamped inductive load test circuit



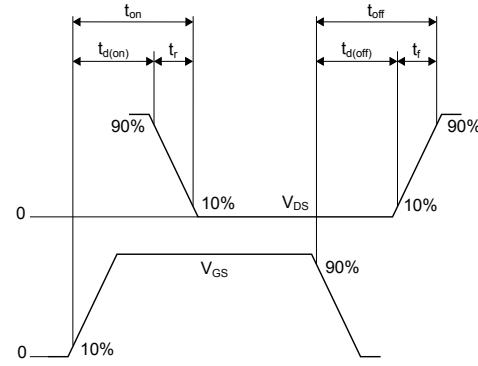
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Figure 17. Unclamped inductive waveform



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Figure 18. Switching time waveform



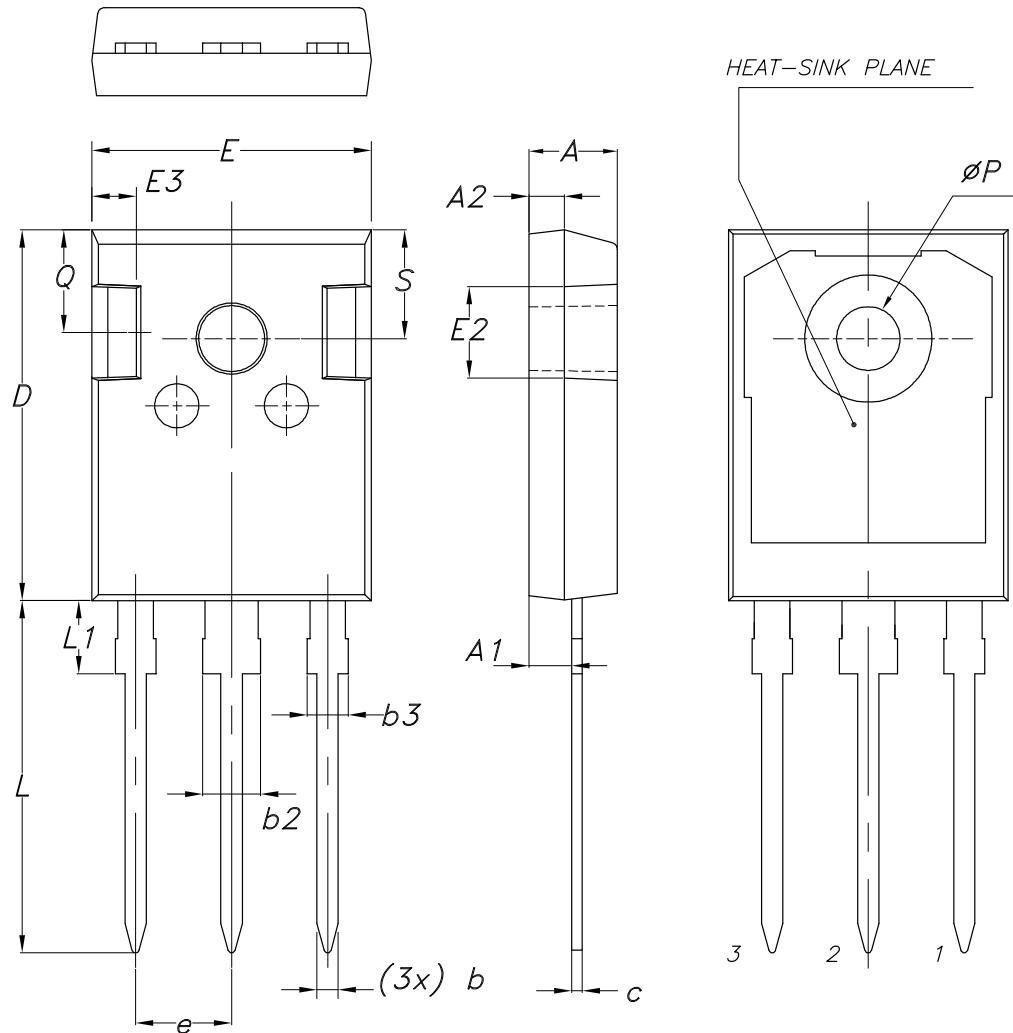
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4**Package information**

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 TO-247 long leads package information

Figure 19. TO-247 long leads package outline



8463846_2_F

Table 8. TO-247 long leads package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

Revision history

Table 9. Document revision history

Date	Version	Changes
07-Aug-2018	1	Initial release. The document status is production data.

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